Abstract

Plating process is one of the most critical steps in the manufacturing process of PCB. The thickness distribution in the hole is an important factor in double sided and also multilayered PCB. Here the plating process is carried using pulse reverse plating on the printed circuit board. Pulse Reverse Electroplating is similar to DC plating but it has a square wave along with a periodic reverse current.[1] In periodic reverse current process a layer is produced on the cathode surface with a lower metal Concentration. Periodic reverse current help to obtain a plating thickness which is uniform in nature and also in nano structured grain size which results in high binding of the metal with the substrate.
Effect of Pulse Reverse Plating using Silver on Printed Circuit Boards

References

- M. S. Chandrasekar, Malathy pushpavanam 2008. “Pulse and reverse pulse plating-conceptual, advantages and applications” electrochimica Acta 53313-3322
- Erb U, T. Turi, 1995 “Nanostuctured Material”, Material science and Engineering 6, pp 533

Index Terms

Computer Science
Emerging Trends in Technology

Keywords
Pulse reverse plating PCB silver Nanostructured coating current density